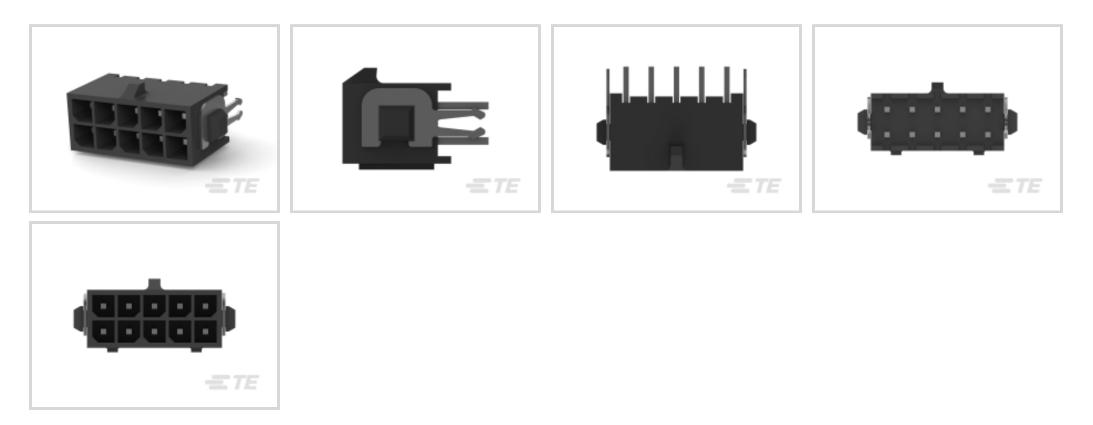
4-794680-0 - ACTIVE

MATE-N-LOK | Micro MATE-N-LOK

TE Internal #: 4-794680-0 Rectangular Power Connectors, Header, Plug, Wire-to-Board, 10 Position, 3 mm [.118 in] Centerline, Printed Circuit Board, UL 94V-0, Micro MATE-N-LOK

View on TE.com >

Connectors > Power Connectors > Rectangular Power > Rectangular Power Connectors



Rectangular Power Connector Type: Header Connector & Housing Type: Plug Connector System: Wire-to-Board

Number of Positions: 10

Centerline (Pitch): 3 mm [.118 in]

Features



Product Type Features

Header Type	Fully Shrouded
Rectangular Power Connector Type	Header
Connector & Housing Type	Plug
Connector System	Wire-to-Board
Sealable	No
Connector & Contact Terminates To	Printed Circuit Board
Configuration Features	
Number of Positions	10
Number of Positions PCB Mount Orientation	10 Vertical
PCB Mount Orientation	Vertical
PCB Mount Orientation Number of Power Positions	Vertical 10
PCB Mount Orientation Number of Power Positions Number of Rows	Vertical 10

Rectangular Power Connectors, Header, Plug, Wire-to-Board, 10 Position, 3 mm [.118 in] Centerline, Printed Circuit Board, UL 94V-0, Micro MATE-N-LOK



Matte Without 5 A Without Pin Tin Tin 2.54 - 7.62 µm[100 - 300 µin] 3.81 µm[150 µin] 3.43 mm[.135 in] Through Hole - Solder Without Polarization
5 A Without Pin Tin Tin 2.54 - 7.62 μm[100 - 300 μin] 3.81 μm[150 μin] 3.43 mm[.135 in] Through Hole - Solder
Without Pin Tin Tin 2.54 - 7.62 μm[100 - 300 μin] 3.81 μm[150 μin] Starm[.135 in] Through Hole - Solder Without
Pin Tin Tin 2.54 - 7.62 μm[100 - 300 μin] 3.81 μm[150 μin] 3.43 mm[.135 in] Through Hole - Solder Without
Tin 2.54 - 7.62 μm[100 - 300 μin] 3.81 μm[150 μin] 3.43 mm[.135 in] Through Hole - Solder Without
Tin 2.54 - 7.62 μm[100 - 300 μin] 3.81 μm[150 μin] 3.43 mm[.135 in] Through Hole - Solder Without
2.54 – 7.62 µm[100 – 300 µin] 3.81 µm[150 µin] 3.43 mm[.135 in] Through Hole - Solder Without
3.81 μm[150 μin] 3.43 mm[.135 in] Through Hole - Solder Without
3.43 mm[.135 in] Through Hole - Solder Without
Through Hole - Solder Without
Through Hole - Solder Without
Without
Polarization
With
Without
With
Boardlock, Retention Bump
Board Mount
With
Locking Tab
3 mm[.118 in]
Black
High Temperature Nylon
Phosphor Bronze
1.52 mm
100.5 – 1022 CMA
3 mm[.118 in]
1.6 mm[.063 in]

Rectangular Power Connectors, Header, Plug, Wire-to-Board, 10 Position, 3 mm [.118 in] Centerline, Printed Circuit Board, UL 94V-0, Micro MATE-N-LOK



Usage Conditions

Operating Temperature Range	-40 – 105 °C[-40 – 221 °F]
Operation/Application	
Circuit Application	Power
Industry Standards	
CSA Rating	Certified
Glow Wire Material Rating	Material with GWFI 850°C, Material with GWIT ≥ 775°C
UL Flammability Rating	UL 94V-0
Glow Wire Rating	GWT 750°C (Without Flame)
Agency/Standard	CSA
UL Rating	Recognized
CSA File Number	LR7189
VDE Tested	No
Packaging Features	
Packaging Method	Box & Tray, Tray
Packaging Quantity	195

Other

For Use With

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2022 (224) Candidate List Declared Against: JUNE 2022 (224) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Reflow solder capable to 260°C

Rectangular Power Connectors, Header, Plug, Wire-to-Board, 10 Position, 3 mm [.118 in] Centerline, Printed Circuit Board, UL 94V-0, Micro MATE-N-LOK



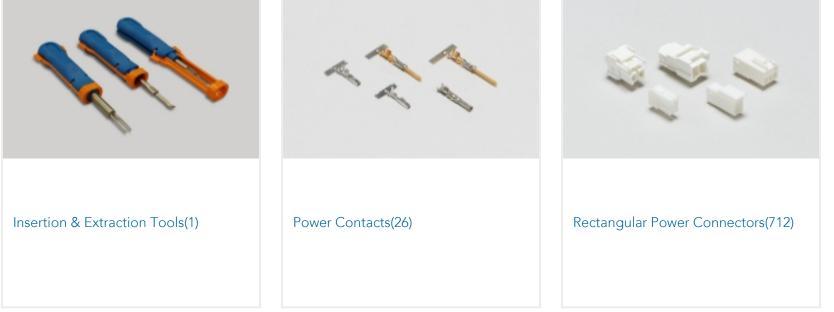
Product Compliance Disclaimer

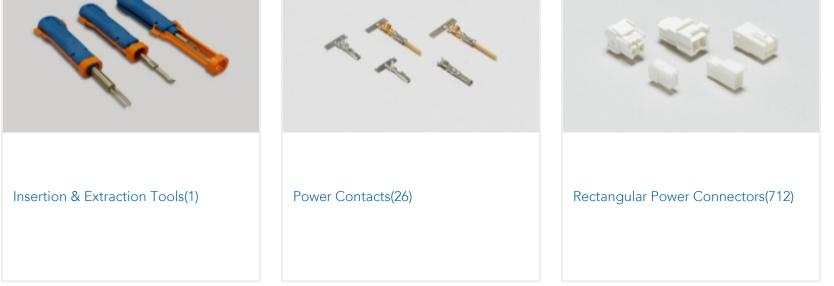
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts



Also in the Series Micro MATE-N-LOK





Documents

CAD Files

3D PDF

3D

Customer View Model

ENG_CVM_CVM_4-794680-0_G.2d_dxf.zip

English

Customer View Model

ENG_CVM_CVM_4-794680-0_G.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_4-794680-0_G.3d_stp.zip

Rectangular Power Connectors, Header, Plug, Wire-to-Board, 10 Position, 3 mm [.118 in] Centerline, Printed Circuit Board, UL 94V-0, Micro MATE-N-LOK



English

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Datasheets & Catalog Pages

SOFT_SHELL_PIN_AND_SOCKET_CONNECTORS_CATALOG

English

MICRO MATE-N-LOK CONNECTOR SYSTEM

English

1773458-4_MICRO_MATE_N_LOK_CONNECTOR_SYSTEM_QRG

English

Product Specifications

Application Specification

English

Product Environmental Compliance TE Material Declaration

English

Agency Approvals VDE Certificate

English